



2025 the 14th International Conference on Material Science and Engineering Technology

As a specialized conference on materials with an thirteen-year history, ICMSET was held in famous universities such as Nanyang Technological University in Singapore, Beijing University of Posts and Telecommunications, Seoul National University and Tokyo University, and achieved remarkable success. This event will include the participation of renowned keynote speakers, oral presentations, posters sessions related to the topics dealt with in the Scientific Program as well as an attractive social and cultural program.

Call for Papers (Topics are included but not limited)

Functional materials

Chemical materials

Cryogenic materials

Nano materials

3D materials

Osaka, Japan

November 21-24, 2025

- Advanced materials
- Biomaterials
- Composite materials
- Energy storage and conversion materials
- Renewable materials
- Polymer science
- Smart/Intelligent materials/Intelligent systems
- Optical/Electronic/Magnetic materials
- Automation, control and information technology
- Magnetic materials and smart materials for specific applications

Keynote Speaker



Prof. Yusuke Yamauchi

The University of Queensland Australia / Distinguished Professor Nagoya University, Japan



Prof. Ramesh K. Agarwal

Washington University in St. Louis USA



Prof. Shaohua Guo

Nanjing University, China

Invited Speaker



Prof. Ildoo Chung

Pusan National University, Korea

Organizing Committees

Conference Chairs

Ramesh K. Agarwal, Washington University in St. Louis, USA Junlei Qi, Harbin Institute of Technology, China

Program Chairs

Hideki Aoyama, Keio University, Japan

Jun Song CHEN, University of Electronic Science and Technology of China, China Aleksey Vedyagin, Boreskov Institute of Catalysis SB RAS, Russia

Publicity Chairs

Marvin Herrera, University of the Philippines Los Banos, Philippines
Mohamed Abdel-Hady Gepreel, Egypt-Japan University of Science and Technology, Egypt
Rinlee Butch Cervera, University of the Philippines Diliman, Philippines
Carlos Rolando Rios-Soberanis, Centro de Investigación Científica de Yucatán, Mexico
Bouchaib Zazoum, Southern Arkansas University, USA

Conference Location

Osaka International Convention Center

Address: 5-3-51 Nakanoshima, Kita-ku, Osaka City, Osaka Prefecture, 530-0005 Japan

Key dates

Submission DeadlineAugust 10th, 2025Notification of AcceptanceAugust 30th, 2025Registration DeadlineSeptember 20th, 2025

Conference Proceedings

After a careful reviewing process, all accepted papers after proper registration and presentation, will be published into Materials Science Forum (MSF) (ISSN: 1662-9752), which submitted for Scopus.

Publication History

The previous ICMSET conference proceedings has been indexed by SCOPUS successfully!

ICMSET 2023 - Scientific Books Collection Vol. 130

ISBN: 978-3-0357-1790-7 | SCOPUS

ICMSET 2022 - Materials Science Forum(MSF) Vol. 1087,

ISBN: 978-3-0357-1838-6 | SCOPUS

ICMSET 2021 - Materials Science Forum(MSF) Vol. 1053,

ISBN: 978-3-0357-2684-8 | SCOPUS

ICMSET 2020 - Materials Science Forum(MSF) Vol. 1023,

ISBN: 978-3-0357-1784-6 | SCOPUS, Ei Compendex

ICMSET 2019 - Materials Science Forum(MSF) Vol. 998,

ISBN: 978-3-0357-1606-1 | SCOPUS, Ei Compendex ICMSET 2018 - Materials Science Forum(MSF) Vol. 950,

ISBN: 978-3-0357-1784-6 | SCOPUS, Ei Compendex

ICMSET 2017 - Materials Science Forum(MSF) Vol. 917,

ISBN: 978-3-0357-1213-1 | SCOPUS, Ei Compendex

ICMSET 2016 - Materials Science Forum(MSF) Vol. 890,

ISBN: 978-3-0357-1028-1 | SCOPUS, Ei Compendex

ICMSET 2015 - MATEC Web of Conferences Vol. 30, 2015

Submission

Submissions must be original and should not have been published previously or be under consideration for publication while being evaluated for this conference. (Abstracts are accepted for oral presentation opportunity, not for publication.)

- » Submissions link: http://confsys.iconf.org/submission/icmset2025
- » Full Paper Template: https://www.icmset.com/TTP_template.doc
- » Abstract Template: https://www.icmset.com/Abstract-Template.doc

Co-sponsored by











Supported by

















Media Partner



